



Material Content Data Sheet



Sales Product Name		BSC047N08NS3 G		Issued		19. July 2018		
MA#		MA001508098						
Package		PG-TDSON-8-39		Weight*		114.25 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.414	3.86	3.86	38634	38634
leadframe	non noble metal	iron	7439-89-6	0.049	0.04		426	
	inorganic material	phosphorus	7723-14-0	0.015	0.01		128	
	non noble metal	copper	7440-50-8	48.649	42.60	42.65	425814	426371
wire	non noble metal	copper	7440-50-8	0.061	0.05	0.05	537	537
encapsulation	organic material	carbon black	1333-86-4	0.078	0.07		680	
	plastics	epoxy resin	-	6.134	5.37		53690	
	inorganic material	silicondioxide	60676-86-0	32.611	28.54	33.98	285438	339808
leadfinish	non noble metal	tin	7440-31-5	1.520	1.33	1.33	13305	13305
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1387	1387
solder	noble metal	silver	7440-22-4	0.087	0.08		761	
	non noble metal	tin	7440-31-5	0.070	0.06		609	
	non noble metal	lead	7439-92-1	3.322	2.91	3.05	29073	30443
heatspreader	non noble metal	copper	7440-50-8	0.000	0.00		1	
	non noble metal	iron	7439-89-6	0.000	0.00		1	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.00	1	0
heat sink CLIP	non noble metal	iron	7439-89-6	0.017	0.01		148	
	inorganic material	phosphorus	7723-14-0	0.005	0.00		44	
	noble metal	silver	7440-22-4	0.150	0.13		1313	
	non noble metal	copper	7440-50-8	16.910	14.80	14.94	148010	149515
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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